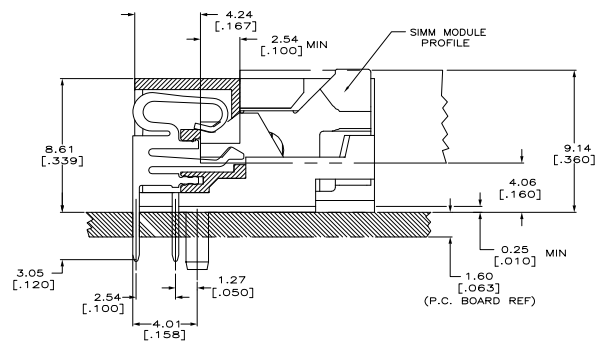
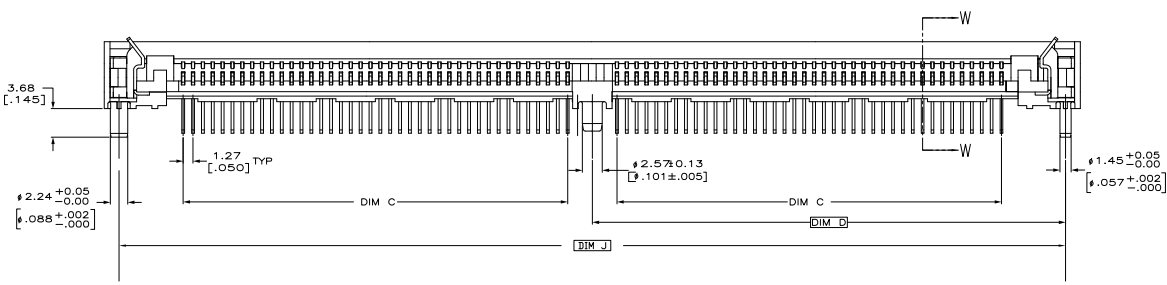
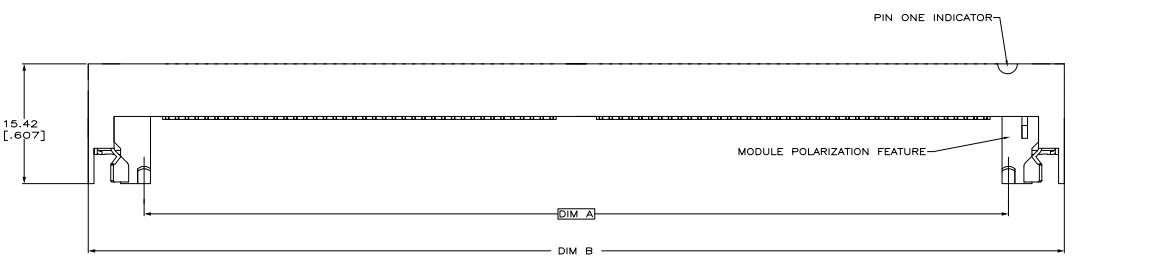


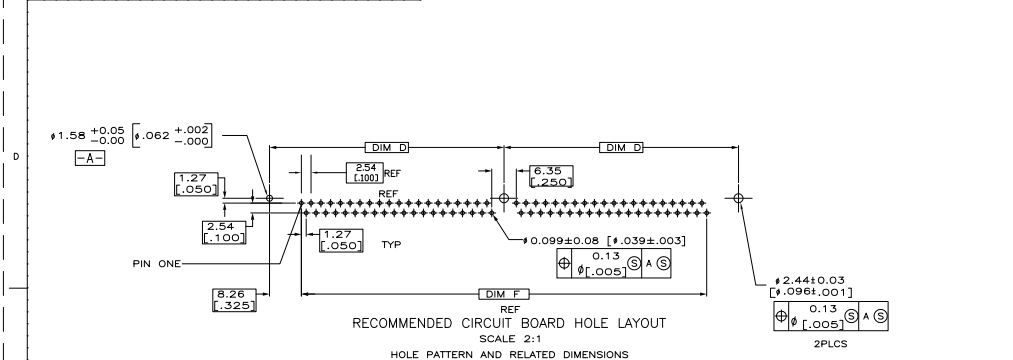
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REV	DATE	DESCRIPTION	BY	CHK	APP
00					
A		REVISED PER ECR-06-022549			200806 S.Y. S.Y.



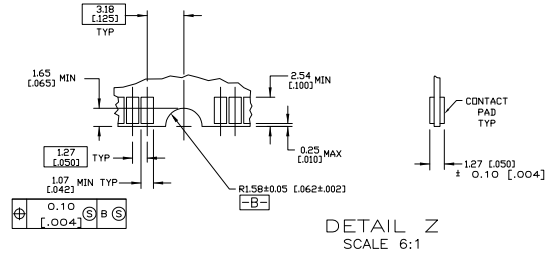
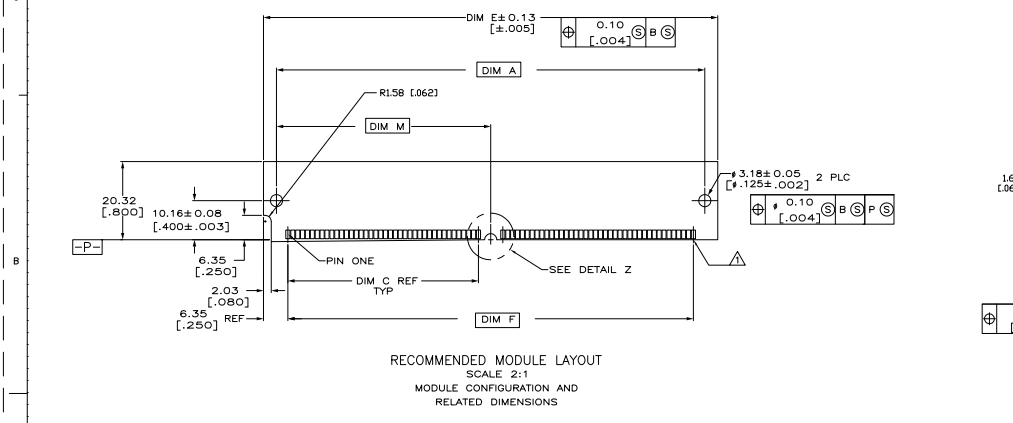
SECTION W-W  
 SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	REV	BY	CHK	APP
DRAWING: HSG-GLASS REF		DATE	REV	BY	CHK	APP
DESIGNED BY: CHEN YAO		DRAWN BY: CHEN YAO		CHECKED BY: CHEN YAO		
APPROVED BY: CHEN YAO		DATE: 200806		SCALE: 8:1		
PART NO: 1.27 (050) CL ASSY		REV: 4.06 (1.163) HSGHIT		REWORKED TO: ---		
CUSTOMER DRAWING		DATE: 200709	REV: G=5.362483	SCALE: 8:1 SHEET: 1 OF 2		



△ FOR OPTIMUM PERFORMANCE, CONTACT PAD PLATING SHOULD BE SMOOTH AND FLAT. COPPER CONTACT PADS ARE TO BE OVERPLATED WITH .00127[.00050] MIN THK NICKEL FOLLOWED WITH 0.00101[.00040] MIN THK GOLD PLATING.

△ CONTACT MATING AREA: 0.00076 [.00030] MIN THICK GOLD. SOLDER TAIL: 0.00005[.000002] MIN THK GOLD. UNDERPLATE: 0.00127[.00050] MIN THK NICKEL OVER ENTIRE CONTACT.



50.60 [±1.992]	111.76 [±4.400]	95.25 [±3.750]	107.95 [±4.250]	55.88 [±2.200]	44.45 [±1.750]	115.57 [±4.550]	101.19 [±3.984]	72	7-5382483-2
DIM M	DIM J	DIM F	DIM E	DIM D	DIM C	DIM B	DIM A	POSN	PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY	SHANGHAI	YAO ELECTRONICS CORPORATION
DRAWN BY	JIANHONG LIU	CHECKED BY	SHANGHAI	Shanghai, P.R.China, 200233
DATE		DATE		
SCALE		SCALE		
TITLE	ONE SIDE BOARD	DATE	1.27 [±.050] CL ASSEMBLY	1.27 [±.050] CL ASSEMBLY
PROJECT		PROJECT	4.08 [±.160] HGT	4.08 [±.160] HGT
DRAWING NO.		DRAWING NO.	A100779	A100779
CUSTOMER DRAWING		CUSTOMER DRAWING	3-382483	3-382483
SHEET	4/1	SHEET	2/2	2/2